



2821

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

KIAN TENG ENG ET AL.

Serial No. 09/766,477 (TI-22944.2)

Filed January 19, 2001

For: VERTICAL BALL GRID ARRAY INTEGRATED CIRCUIT PACKAGE

Art Unit 2827

Examiner James M. Mitchell

Commissioner for Patents
Washington, D. C. 20231

Sir:

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MAR 18 2003
TECHNOLOGY CENTER 2800**AMENDMENT UNDER 37 C.F.R. 1.111**

In response to the Office action dated February 11, 2003, please amend the above identified application as follows:

In the claims:

Claims 1 to 20 (canceled).

Claim 21 (currently amended) A process of providing a high density module produced by a process comprising the steps of:

[obtaining] providing a circuit board having a substantially planar top surface for connection to at least one integrated circuit package; and

electrically connecting at least one integrated circuit package having a major surface and side minor surfaces extending from said major surface [terminal], at least one of said side surfaces having electrical side surface terminals thereon in intimate contact